To the Honorable Commissioner of Patents and Trademarks

1. Name of conveying party(ies):
   (a) Yoon, Mee-Young
   (b) Lee, Sang-In;
   (c) Lim, Hyun-Seok
   Additional name(s) of conveying party(ies) attached? □ Yes  X No

2. Name and address of receiving party(ies):
   Name: Samsung Electronics Co., Ltd.
   Internal Address: 
   Street Address: 416, Maetan-dong, Paldal-ku, Suwon-city, Kyungki-do, Republic of Korea
   City ___________ State _______ ZIP _______
   Additional name(s) & address(es) attached? □ Yes  X No

3. Nature of Conveyance:
   ☑ Assignment  □ Merger
   □ Security Agreement  □ Change of Name
   □ Other
   Execution Date: (a) September 16, 1999; (b) & (c) September 15, 1999

4. Application number(s) or patent number(s):
   If this document is being filed together with a new application, the execution date of the application is: (a) September 16, 1999; (b) & (c) September 15, 1999
   A. Patent Application No.(s) - 07/397,616
      Title: Semiconductor Device Fabrication Method Using An Interface Control Layer To Improve A Metal Interconnection Layer
      Additional numbers attached? □ Yes  X No

5. Name and address of party to whom correspondence concerning document should be mailed:
   Name: David T. Millers
   Internal Address: SKJERVEN, MURRILL, MacHERSON, FRANKLIN & FRIEL LLP
   Street Address: 25 METRO DRIVE, SUITE 700
   City SAN JOSE State CA ZIP 95110

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): $40.00
   ☑ Authorized to be charged to Deposit Account 19-2386
   ☑ Charge Deposit Account 19-2386 for any additional fees required for this conveyance and credit deposit account 19-2386 any amounts overpaid

8. Statement and signature.
   To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

   David T. Millers  9-16-99
   Name of Person Signing  Signature  Date

   09/24/1999 DMUYEN 00000137 192386 09397616
   01 FC:561 40.00 CH

   Total number of pages comprising cover sheet: 1
ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we

Mee-Young Yoon of 506-1703, Muijigae Maegul Chonggu Apt., 221, Bundang-gu, Seongnam-city, Kyungki-do, Republic of Korea

Sang-in Lee of 104-706, hanguk 1-ch a Apt., Maetan 2-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea

Hyun-seok Lim of San 7-1, Nongseo-ri, Kiheung-eub, Yongin-city, Kyungki-do, Republic of Korea

hereby sell, assign and transfer to Samsung Electronics Co., Ltd., a Korean corporation, having a place of business at 416, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea, its successors and assigns, the entire right, title and interest throughout the world in our invention in

Semiconductor Device Fabrication Method Using An Interface Control Layer To Improve A Metal Interconnection Layer

for which we have executed a United States patent application or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, in their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 16 day of September, 1999.

Mee-Young Yoon

Executed this ____ day of ______________________, 1999.

Sang-in Lee

Executed this ____ day of ______________________, 1999.

Hyun-seok Lim
ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we

Mee-Young Yoon

of 306-1703, Mulligea Masul Chonggu Apt., 221, Bundang-gu, Seongnam-city, Kyungki-do, Republic of Korea

Sang-in Lee

of 104-7D6, hanguk 1-chu Apt., Maseon
2-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea

Eui-joo Lee

of San 7-1, Nongseo-ri, Kihyeung-eub, Yongin-city, Kyungki-do, Republic of Korea

Hyun-Seok Lim

hereby sell, assign and transfer to Samsung Electronics Co., Ltd., a Korean corporation, having a place of business at 416, Maseon-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea, its successors and assigns, the entire right, title and interest throughout the world in our invention in

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for which we have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignees to apply for patents in foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignees, their successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignees, its successors and assigns.

Executed this ___ day of __________________, 1999.

Mee-Young Yoon

Executed this 14th day of Sep. __________, 1999.

Sang-in Lee

Executed this 15th day of September __________, 1999.

Hyun-Seok Lim

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RECORDED: 09/16/1999